



ORION "410" Di

ORION™ 410 Di no-clean dispensing grade solder paste is carefully formulated to confer high activity soldering and yet, leaves very low clear, benign residues.

- Halide-free.
- High activity.
- Low and safe residue.
- Lead-free option available.
- Extended tack-life (>48 hours).
- Excellent slump resistance.

ORION™ 410 Di no-clean dispensing grade solder paste is made to strict quality assurance standards.

Alloys	Metal content (%)	Viscosity (cP)
Sn63Pb37	86	300,000 – 500,000
Sn62PbAg2	86	300,000 – 500,000
Sn95.5Ag3.8Cu0.7	86	300,000 – 500,000
+ Others	On request	

Dispensing

ORION™ 410Di has been designed for most types of solder paste dispensing equipment equipped with needles down to 0.41mm (using 25-45µm powder). Finer dispensing needles require 15-30µm powder.

Ambient Conditions

18 - 25°C and 35% - 70% RH. Minimise exposure of paste to direct air flow.

Cleaning of Nozzles and Tools

Use MBO Easy-Purge 400 conditioning gel. Contact MBO for further information.

Reflow

Heating Methods

Hot air convection, infrared, vapour phase, hot plate, hot bar, laser and others. Aerobic or inerted reflow.

Heating Profile

See suggested reflow profile for specific alloy.

Cleaning Equipment (if required)

Spray, immersion, vapour degreaser or scrubber,

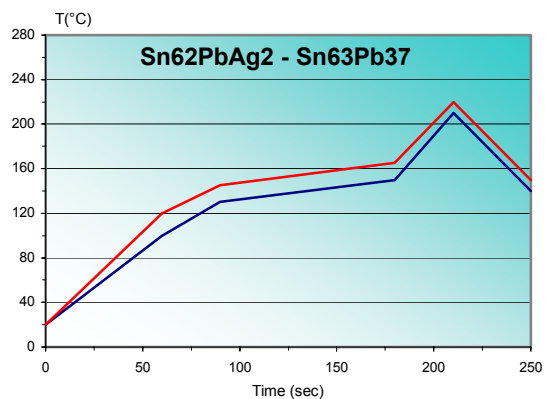
Cleaning solvents

Most stencil cleaners and saponifiers. Contact MBO for further information.

Temperature

35-60°C.

Spray Pressure: 20 to 40 psi.



Packaging

Syringes and cartridges of 25g, 75g - others on request. Contact MBO.

Storage

In original container between 5 and 10°C for up to 3 months. Wait until the container has reached ambient temperature before opening to avoid water condensation on the surface of the paste. Once opened, do not return to the fridge. Should be stored at ambient conditions and consumed within one week.